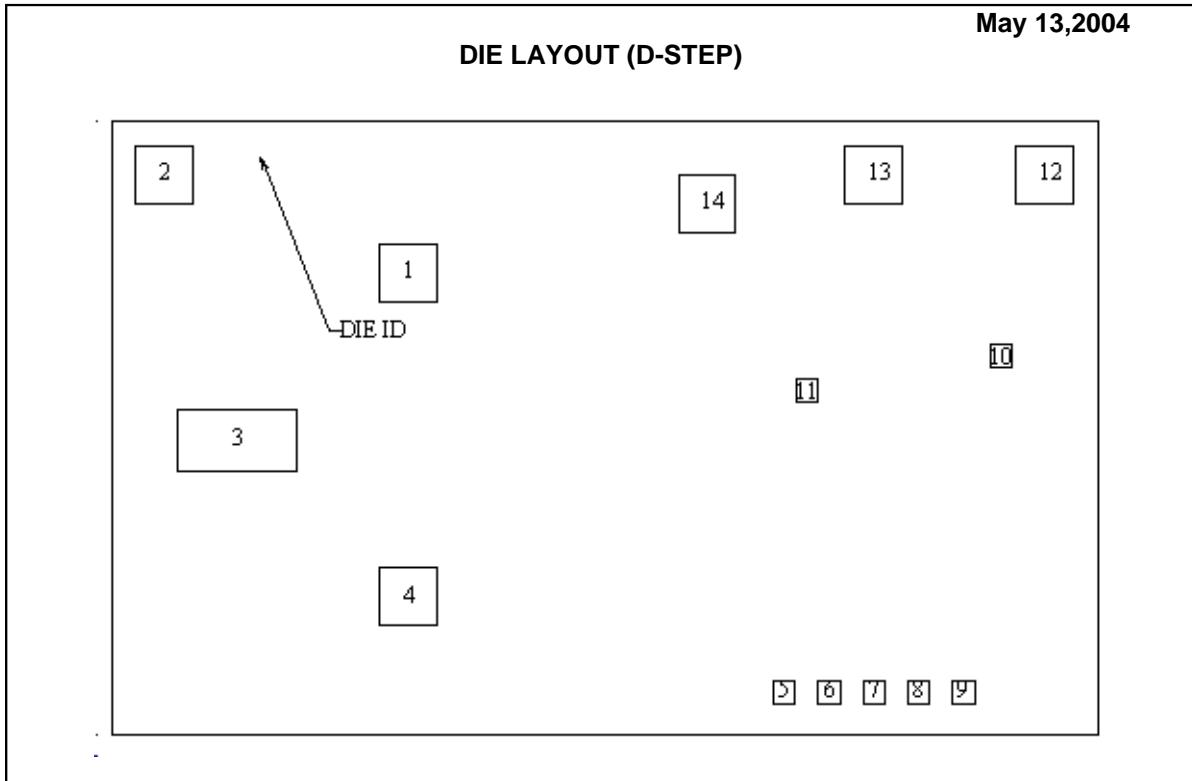


**LM2990-5.0 MD8 MW8
NEGATIVE LOW DROPOUT REGULATOR**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM2990D	Bond Pad Opening Size (min)	190µm x 190µm
Die Step	D	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	3277µm x 2032µm 129.0mils x 80.0mils	Back Side Connection	INPUT
Thickness	406µm Nominal		
Min Pitch	148µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

"Not compatible with aluminum wire ultrasonic wedge bonding"

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Die Bond Pad Coordinate Locations (D-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL NAME	PAD# NUMBER	XY COORDINATES		PAD SIZE		
		X	Y	X	Y	
INPUT	1	-652	513	190	x	190
OUTPUT	2	-1463	840	190	x	190
OUTPUT	3	-1222	-42	400	x	200
INPUT	4	-652	-560	190	x	190
NC	5	594	-877	75	x	75
NC	6	745	-877	75	x	75
NC	7	893	-877	75	x	75
NC	8	1041	-877	75	x	75
NC	9	1189	-877	75	x	75
NC	10	1315	239	75	x	75
NC	11	670	126	75	x	75
NC	12	1461	840	190	x	190
NC	13	891	840	190	x	190
GND	14	339	746	190	x	190

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K

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